

Search Notes

Application No.

10/685,485

Examiner

Stephen W. Smoot

Applicant(s)

FANG, JEN KUANG

Art Unit

2813

SEARCHED

Class	Subclass	Date	Examiner
438	108	5/14/2004	SWS
438	122	5/14/2004	SWS
438	124	5/14/2004	SWS
438	127	5/14/2004	SWS
438	612	5/14/2004	SWS
438	613	5/14/2004	SWS
438	615	5/14/2004	SWS
Updated	Above	11/3/2004	SWS

*S.W.S.**S.W.S.***INTERFERENCE SEARCHED**

Class	Subclass	Date	Examiner

**SEARCH NOTES
(INCLUDING SEARCH STRATEGY)**

	DATE	EXMR
Considered all citations from parent application.	5/14/2004	<i>S.W.S.</i> SWS
Key Words: Flip Chip; Heat Sink; Solder Bump - Reflow; Contact Pad - UBM, Underbump Metallurgy.	5/14/2004	<i>S.W.S.</i> SWS
Updated Above Search	11/3/2004	<i>S.W.S.</i> SWS
Search Tools - EAST (attached): USPAT; US PG PUBS; Derwent; EPO; JPO; IBM TDB	5/14/2004 <i>8</i> 11-3-04	SWS <i>S.W.S.</i>